

Financial Results Briefing Material

for the Third Quarter of the Fiscal Year Ending March 2023

JCU CORPORATION

TSE Prime (Stock Code: 4975) February 3, 2023

Summary of Consolidated Financial Results for 3Q FY3/23



Accounting Period of 3Q FY3/23 JCU (non-consolidated): April 1 to December 31, 2022 Overseas subsidiaries: January 1 to September 30, 2022

- China: While demand for PWBs for other high-performance electronic devices subsided after having increased with loT and teleworking as keywords, demand for chemicals increased thanks to the production of PWBs for smartphones staying relatively strong.
 Taiwan: Demand for semiconductor package substrates for high-performance electronic devices and servers remained strong, and demand for chemicals increased significantly.
 South Korea: As a result of demand for the semiconductor market being slacked, demand for chemicals stayed flat because some manufactures of semiconductor package substrates continued reducing inventories.
 Japan: The shortage of semiconductors and parts was alleviated, resulting in increases in automobile production and demand for chemicals.
 China: Recovery in production started as strict activity restrictions were relaxed in early June, resulting in an increase in automobile production. However, demand for chemicals stayed flat.
 - Due to the resumption of postponed projects caused by the pandemic, and the increasing demand for new investment in plating machines in electronics industry, net sales, orders received, and order backlog increased significantly.

Summary of Financial Results for 3Q FY3/23



(Millions of yen) YoY 3Q FY3/22 3Q FY3/23 % Change 20,702 17,841 16.0% Net sales 6,626 7,320 10.5% Operating profit 6,743 7,398 9.7% Ordinary profit Profit attributable to owners 4,620 5,154 11.5% of parent 198.86 yen 176.47 yen Net income per share

Foreign Exchange Rates

(Yen)

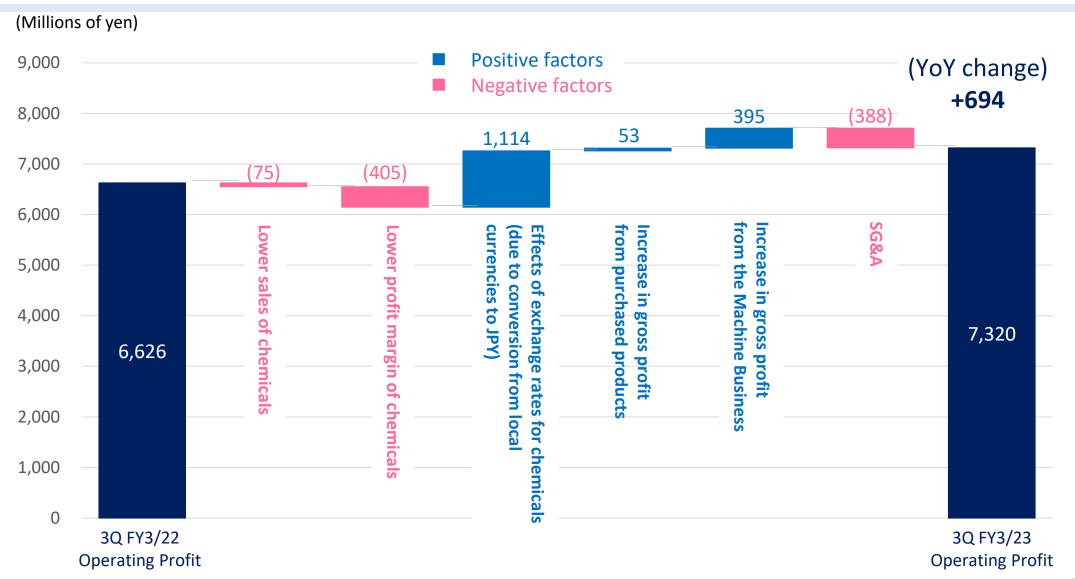


Foreign exchange sensitivity (as at the consolidated year): Changes of about 90 million yen in consolidated operating profit with 1% change in major currency rates listed below

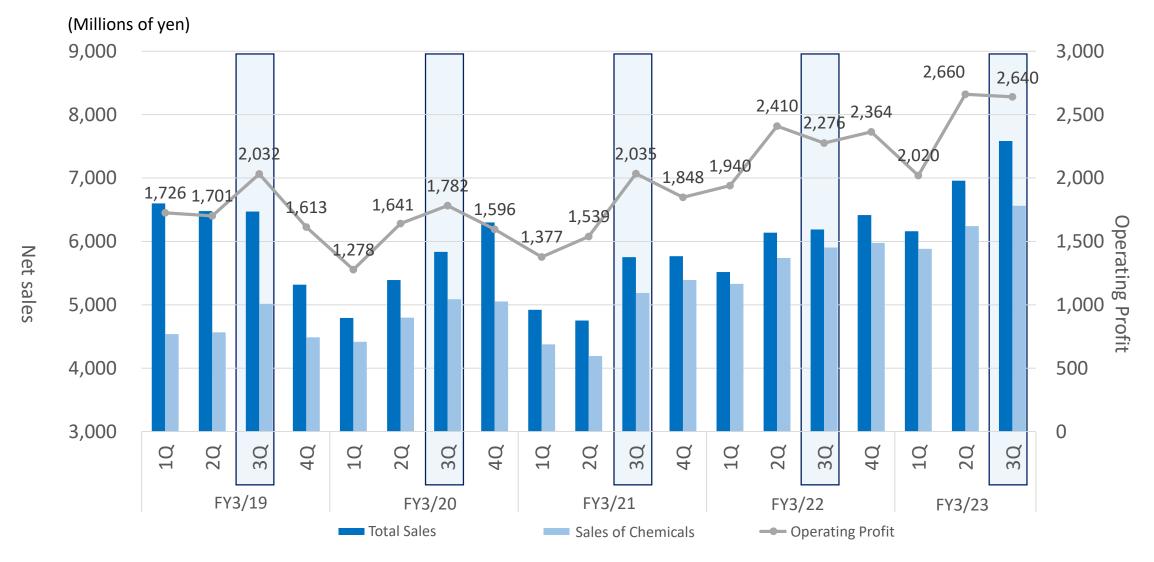
	FY3/22			FY3/23				
	1Q	2Q	3Q	4Q	(Initial forecast)	1Q	2Q	3Q
Chinese yuan (CNY)	16.36	16.66	16.78	17.03	17.20	18.29	18.93	19.35
Taiwan dollar (TWD)	3.77	3.84	3.88	3.93	4.00	4.15	4.28	4.37
Korean won (KRW)	0.0951	0.0964	0.0959	0.0960	0.0940	0.0964	0.0996	0.1008

Note: The average rate for the period is used to translate Chinese yuan, Taiwan dollar and Korean won, our major foreign currencies, to Japanese yen.

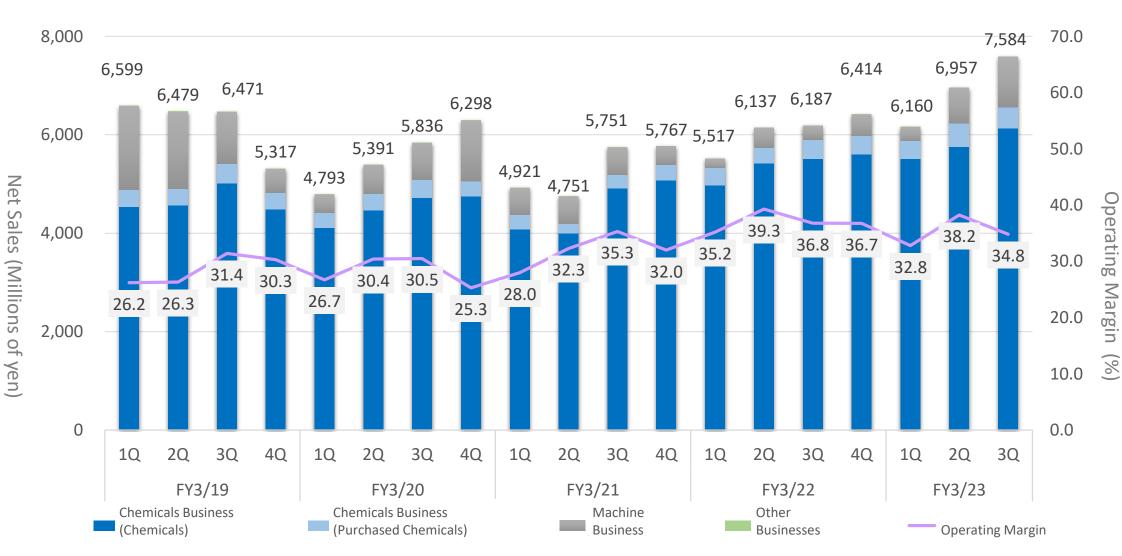
Changes in Consolidated Operating Profit for 3Q FY3/23



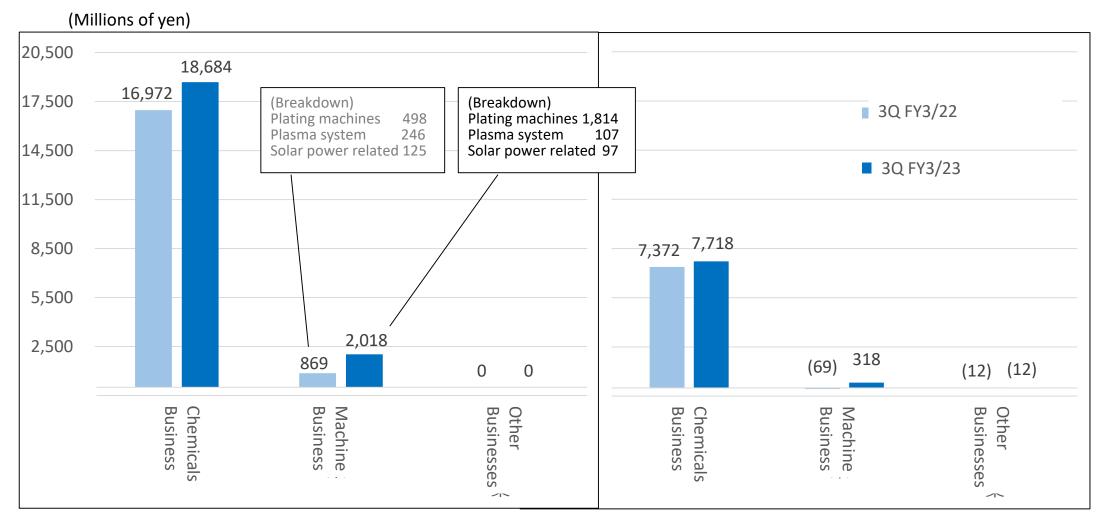
Quarterly Consolidated Financial Results



Quarterly Consolidated Financial Results (By Segment)



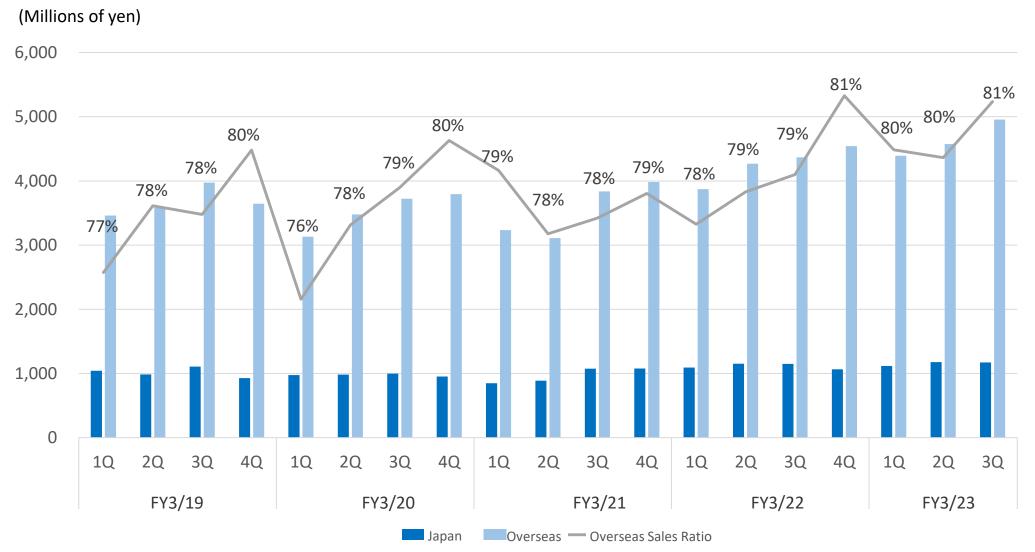
Consolidated Segment Results for 3Q FY3/23



Net Sales

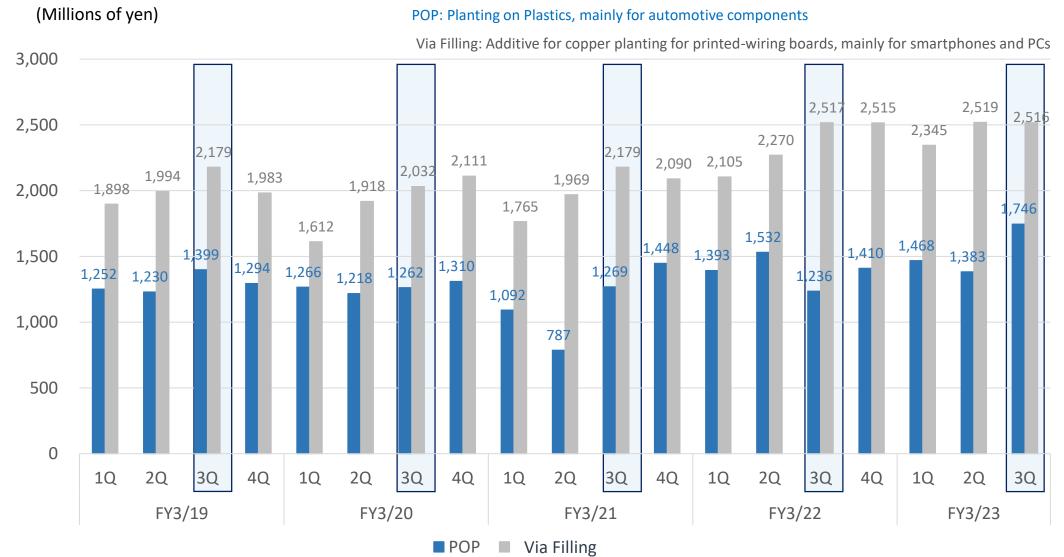
Segment Profit (Loss)

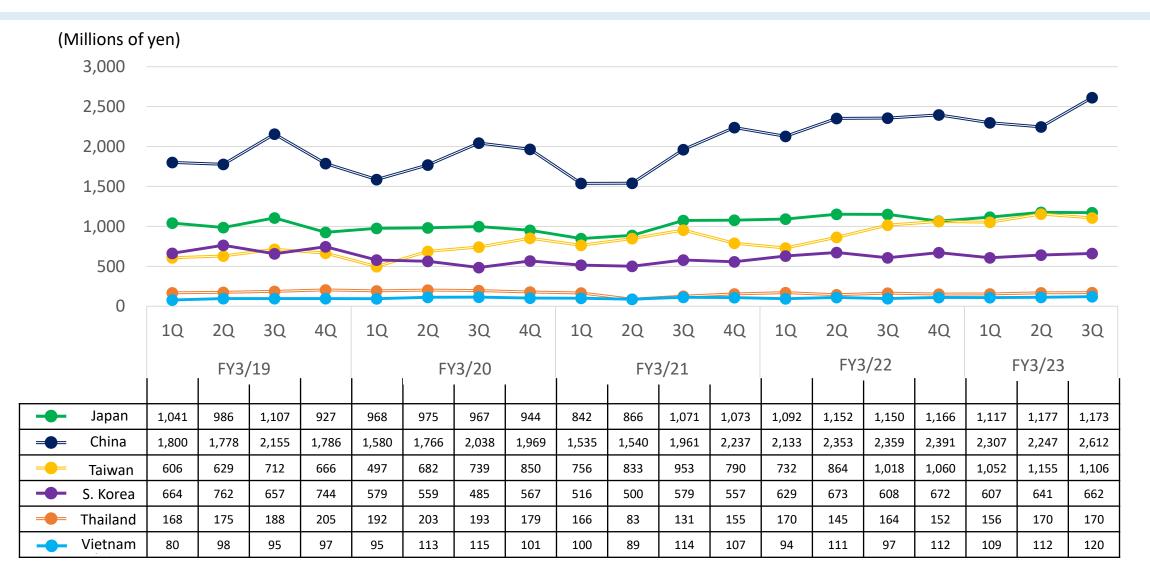
Quarterly Sales of Chemicals in Japan and Overseas



Quarterly Sales of Chemicals for POP and Via Filling

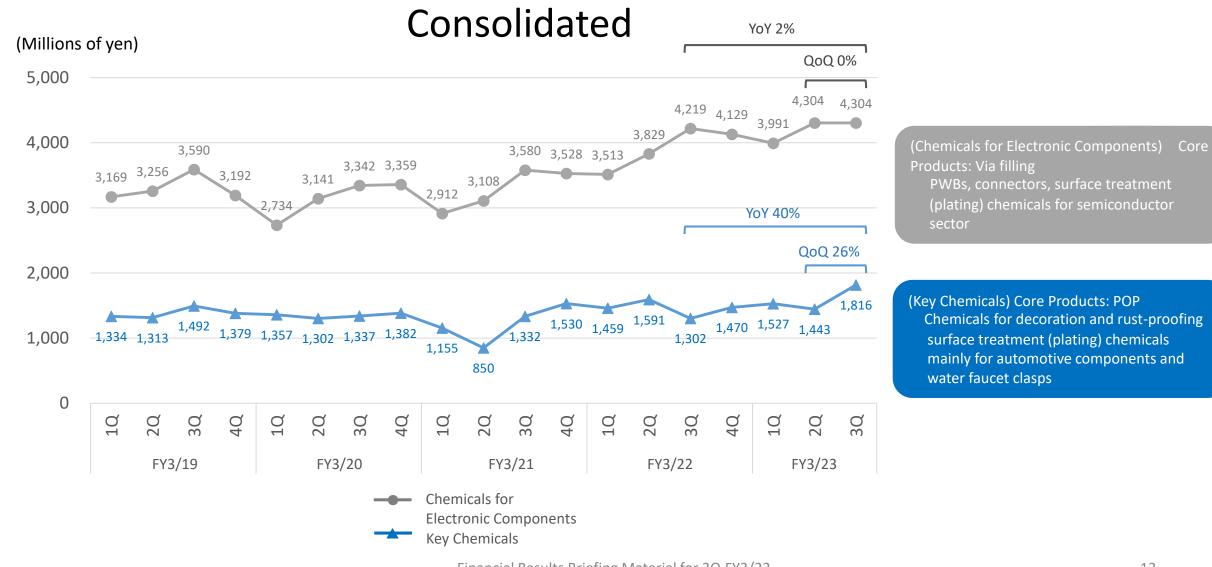


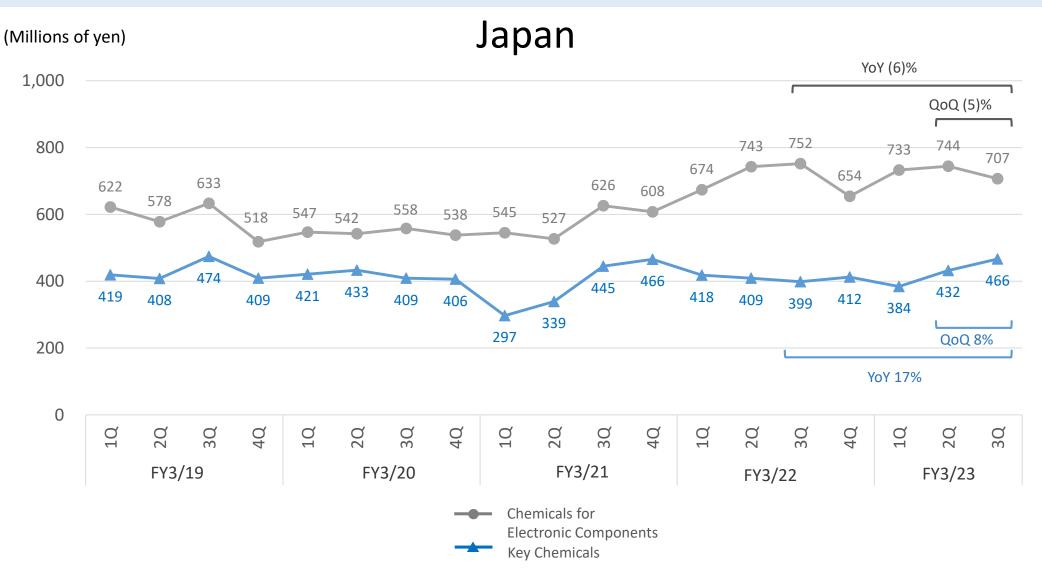




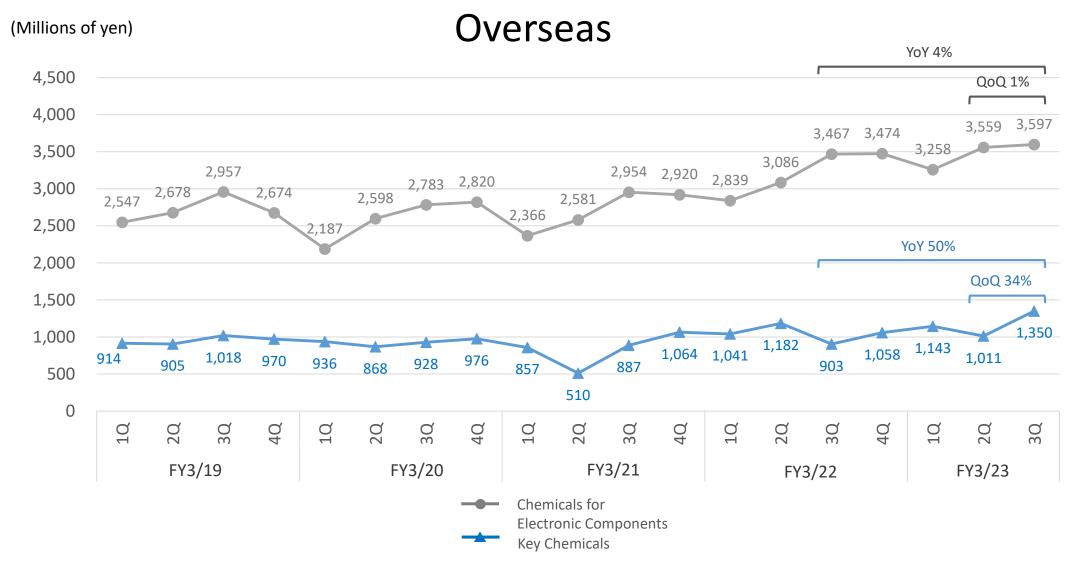
Quarterly Sales of Chemicals by Category



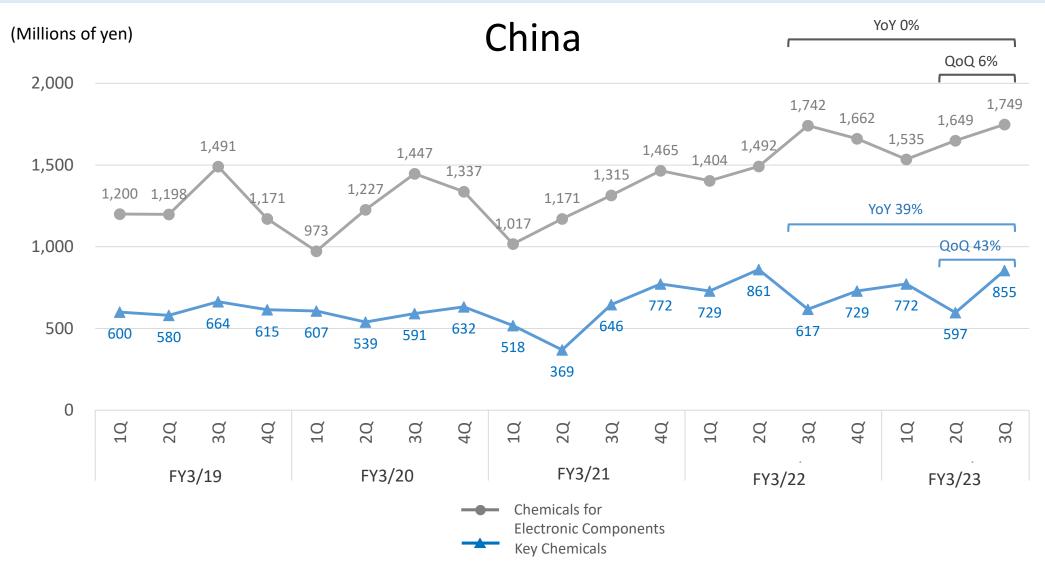


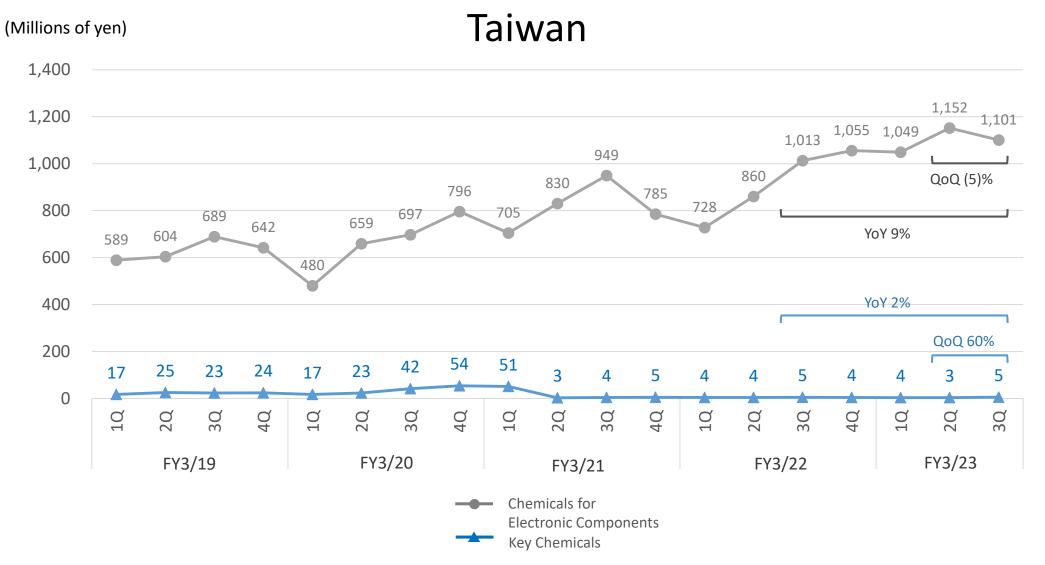




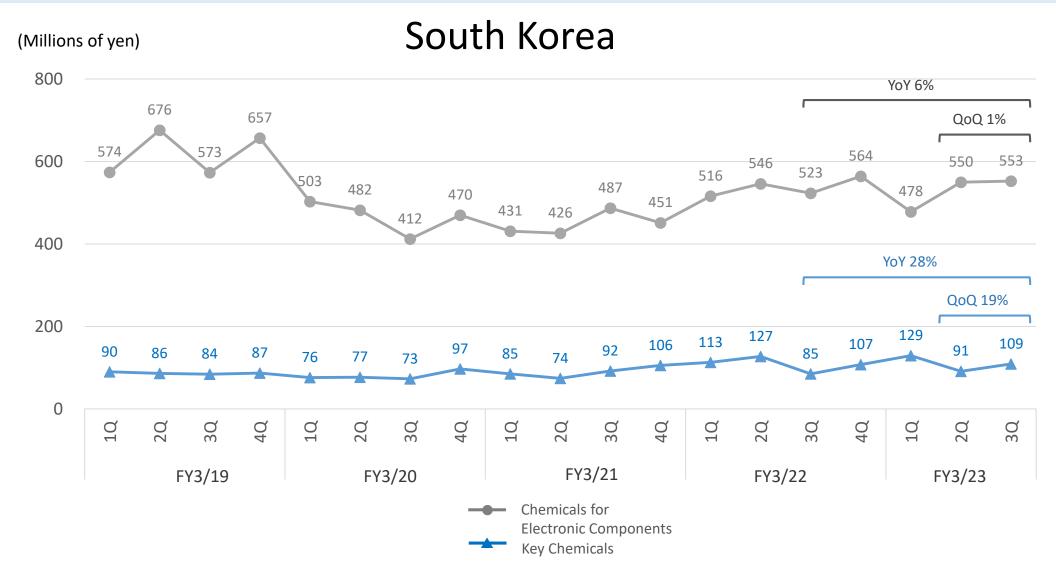












3Q Progress Rate against FY3/23 Forecasts

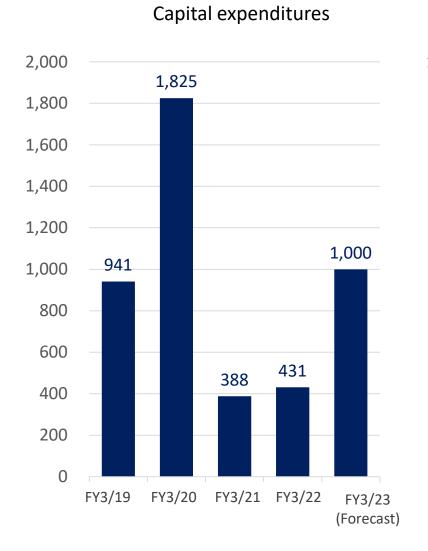


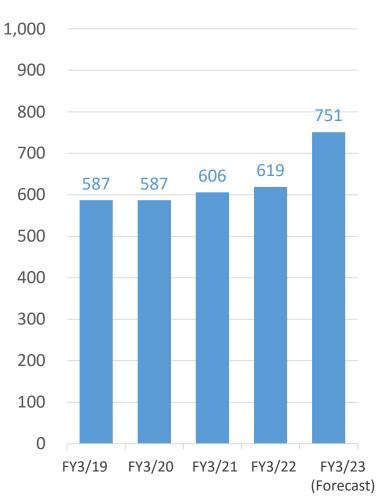
(Millions of yen)

	3Q FY3/23	FY3/23 Forecasts (Revised on May 11, 2022)	Progress rate against full-year forecast
Net sales	20,702	26,500	78.1%
Operating profit	7,320	9,100	80.4%
Ordinary profit	7,398	9,100	81.3%
Profit attributable to owners of parent	5,154	6,300	81.8%
Net income per share	198.86 yen	243.46 yen	-

Capital Expenditures, Depreciation and R&D Expenses

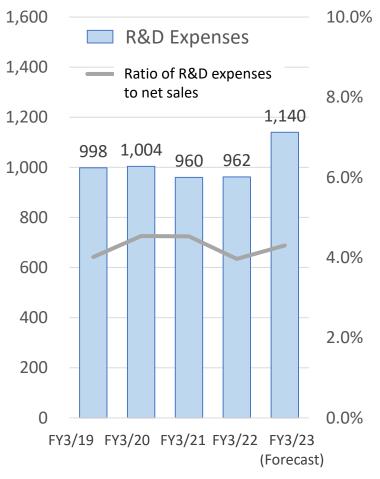






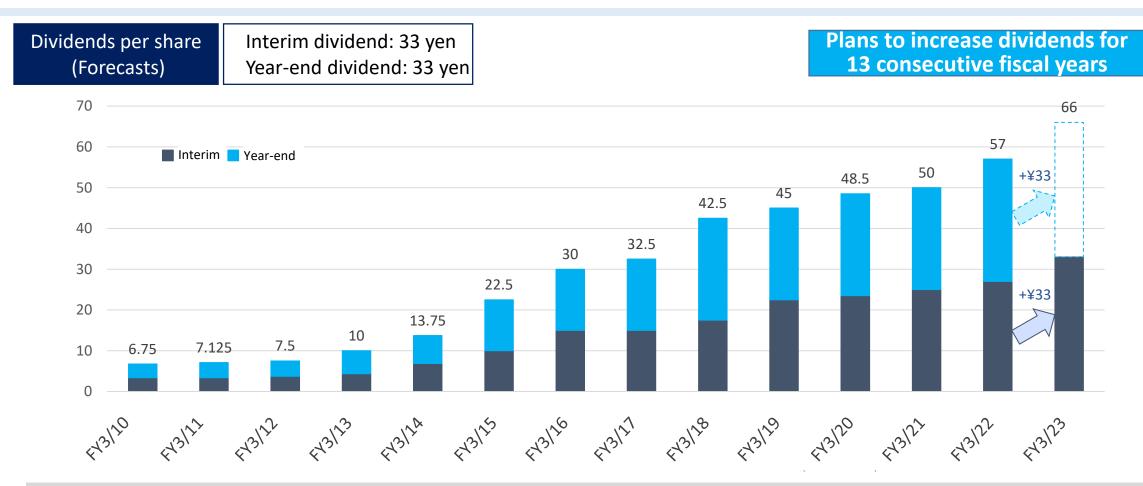
Depreciation

R&D expenses and ratio of R&D expenses to net sales



Dividend Forecast





We will continue to make investments for sustainable growth while securing liquidity on hand and maintaining stable financial base. Our basic dividend policy is to return profits to shareholders through the flexible acquisition of treasury stock, with the aim of continuing the trend of stable dividend increases.

Efforts in Addressing ESG Challenges



JCU aims to become a global company that continues to grow in a sustainable fashion by addressing ESG challenges through its business activities.

Environmental



Development of environmentally responsible products

- Hexavalent chromium-free process for automotive components
- Eco-friendly amine-free DFR stripping process
- Eco-friendly cyanogen-free silver plating process



Governance

CO2 emissions (non-consolidated)

1,198 tons of CO2 (emitted in FY3/21) * Down 17% from those in FY3/14

Social

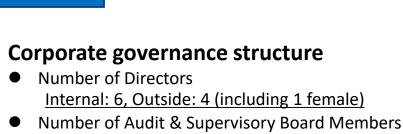


Ratio of female managers (non-consolidated) <u>10.8%</u> (in FY3/21)

ISO 9001 certified overseas production sites



- <u>12 sites in 7 countries</u> (in FY3/21)
- * Japan, China, Taiwan, South Korea, Thailand, Vietnam, and Mexico



Full-time: 1, Outside: 3 (including 1 female)

JCU's CSR report (Japanese only) at https://www.jcu-i.com/csr/download/

Reference



- Company Profile
- Surface Treatment Technology in Future
- Major Distribution Channels
- Major Products
- Usages of Chemicals and Typical Final Products

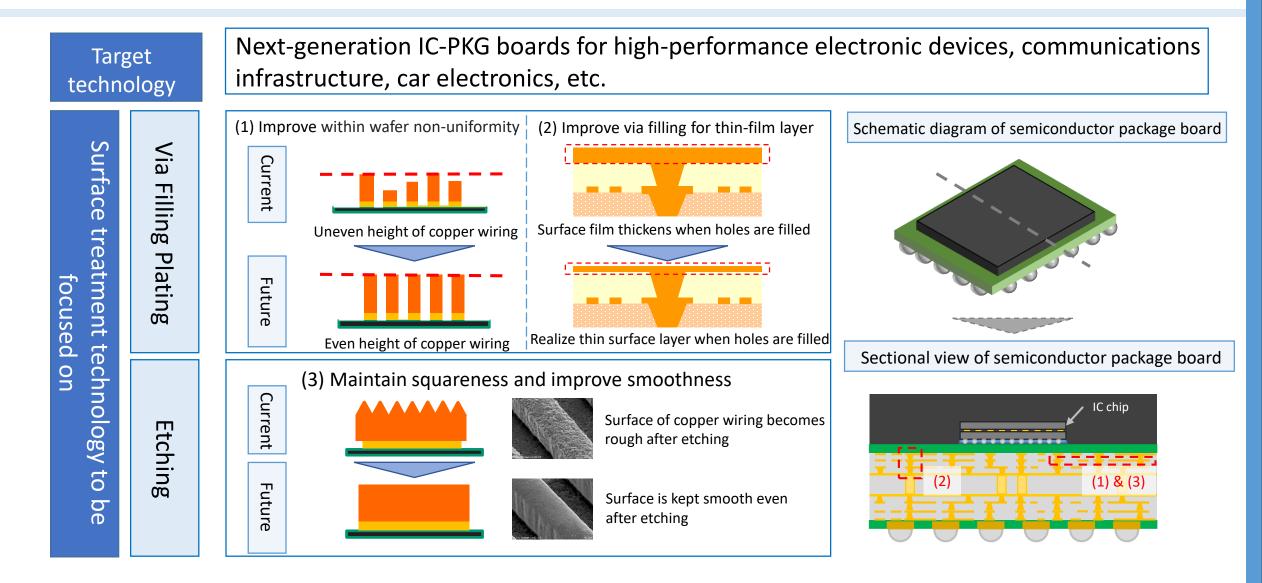
Company Profile



Founded in	: Decer	nber 1957	
Established on	: April 1	April 1, 1968	
Capital stock	: 1,245	1,245 million yen	
Annual sales	•	onsolidated: 12.7 billion yen / Consolidated: 24.2 billion yen e fiscal year ended March 31, 2022)	
Head office	: TIXTO	TIXTOWER UENO 16F, 8-1 Higashiueno 4-chome, Taito-ku, Tokyo	
Lines of business	•	Manufacturing and sale of surface treatment chemicals, surface treatment machines, and related materials	
Representative Directors	: Masas	shi Kimura, Chairman and CEO	
Employees	-	onsolidated: 242 / Consolidated: 548 ^{Narch 31, 2022)}	
ISO Certificates	ISO9001 ISO14001	Production Headquarters, Head Office Sales and Marketing Department, and R&D Center (JCQA-0281) Production Headquarters and R&D Center (JCQA-E-0143)	
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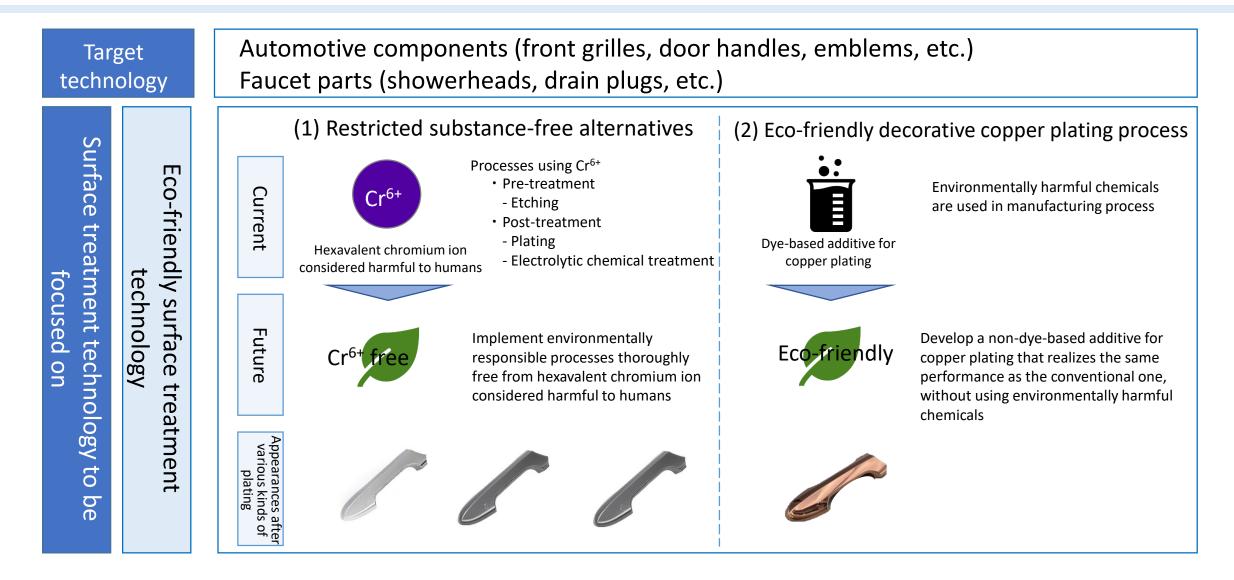
Surface Treatment Technology in Future — Electronic Components—



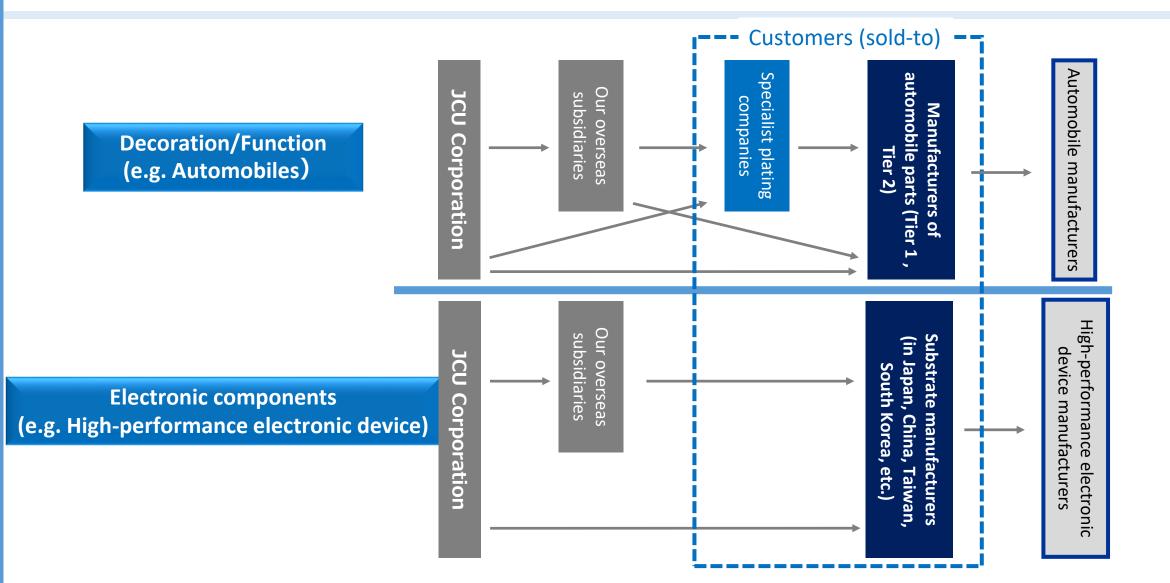


Surface Treatment Technology in Future — Decoration & Function—





Major Distribution Channels





Major Products



Chemicals	For decoration and rust-proofing (Key chemicals)	Automotive parts (front grilles, door handles, emblems, etc.) Faucet parts (water supply equipment, showerheads, drain plugs, etc.) Construction materials (bolts, nuts, etc.)
Business	For electronic components (Chemicals for electronic components)	PWBs (reversible and multilayer substrates, build-up boards, package substrates, etc.) Electronic components (lead frames, chip components, connectors, etc.) Semiconductors (silicon wafers)
Machine	Fully-automated surface treatment equipment	Fully-automated equipment from input of materials to completion of the plating process
hine	Peripheral equipment	Manufacturing and sale of filtration machines and other peripheral equipment to be attached to surface treatment equipment
Business	Automatic analytical control systems	Automatic management of plating solutions by analyzing concentrations of chemicals and adding chemicals when an insufficient level is detected
ess	Plasma system	Etching and washing devices for PWBs as part of pre-plating processes

Usages of Chemicals and Typical Final Products



	Description of term	Final products	
Key chemicals	Surface treatment (plating) chemicals for decorative and rust-proofing purposes such as those for providing a metal appearance and preventing rust.	Automotive parts, faucet parts and construction materials	
POP (Plating on Plastics) chemicals	Major products for key chemicals Chemicals for metal coating on plastics	(Automotive parts) Front grilles, emblems, etc. (Faucet parts) Showerheads, water faucet cocks, etc.	
Other key chemicals	Chemicals for metal coating on metallic materials such as copper and steel	(Construction materials) Screws, hinges, etc.	
Chemicals for electronic components	Plating chemicals for manufacturing PWBs, such as a circuit for electronic signals and an electrical contact for electronic components	5G-related components, data centers and other infrastructures and high-performance electronic devices	
Via filling chemicals (for PWBs/motherboards)	Copper plating chemicals for formulating interconnection onto PWBs/motherboards embedded in electronic products	(5G-related components) 5G base stations, in-vehicle PWBs, smart home	
Via filling chemicals (for semiconductor package boards)	Copper plating chemicals for formulating interconnection onto PWBs (semiconductor packages boards) for the purpose of protecting a semiconductor chip from the external environment and mounting to PWBs	appliances, etc. (Data centers and other infrastructures) Motherboards for communication servers etc. (High-performance electronic devices)	
Other	Plating chemicals for connecters and lead frames, etching chemicals for scraping unnecessary copper when formulating interconnection onto motherboards or semiconductor packages boards	Smartphones, PCs, tablets, game consoles, etc.	



This material contains current plans and forecasts of future performance of JCU CORPORATION. These plans and forecast figures are prepared by the Company based on currently available information. This material does not give any assurance or guarantee of the Company's future financial performance and actual results may differ substantially from these plans for a number of conditions or developments in the future.

> JCU CORPORATION's website URL: https://www.jcu-i.com/

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